

| Parameter             | Rating | Units                |
|-----------------------|--------|----------------------|
| Load Voltage          | 800    | $V_P$                |
| Load Current          | 100    | $mA_{rms} / mA_{DC}$ |
| On-Resistance (max)   | 50     | $\Omega$             |
| Input Control Current | 2      | mA                   |

### Features

- 7mm Separation of Output Pins
- 800V<sub>P</sub> Blocking Voltage
- 5000V<sub>rms</sub> Input/Output Isolation
- Low Drive Power Requirements
- No EMI/RFI Generation
- Small Surface Mount Package
- Flammability Rating UL 94 V-0

### Applications

- Instrumentation
- Multiplexers
- Data Acquisition
- Electronic Switching
- I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- Medical Equipment—Patient/Equipment Isolation
- Automotive High-Voltage Circuitry
- Industrial Controls

### Description

Specially designed to provide 7mm of separation between the two output pins, IXYS Integrated Circuits' PLA171 is a single-pole, normally open (1-Form-A) Solid State Relay that uses optically coupled MOSFET technology to provide an enhanced input to output isolation of 5000V<sub>rms</sub>.

Its optically coupled outputs, which use the patented OptoMOS architecture, are controlled by a highly efficient infrared LED.

The PLA171 is designed to replace, and offers superior reliability over, electromechanical relays. This device provides bounce-free switching in a compact surface-mount package.

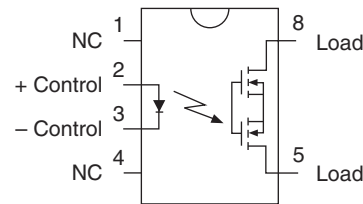
### Approvals

- UL Certified Component: File E76270
- TUV EN 62368-1: Certificate # B 082667 0008

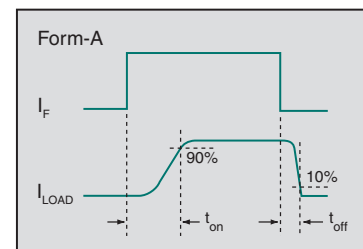
### Ordering Information

| Part #    | Description  |
|-----------|--|
| PLA171P   | 6-Pin (8-Pin Body) Flatpack (50/Tube)                |
| PLA171PTR | 6-Pin (8-Pin Body) Flatpack, Tape & Reel (1000/Reel) |

### Pin Configuration



### Switching Characteristics of Normally Open Devices



## Absolute Maximum Ratings @ 25°C

| Parameter                                       | Ratings     | Units            |
|---|-------------|------------------|
| Blocking Voltage                                | 800         | V <sub>P</sub>   |
| Reverse Input Voltage                           | 5           | V                |
| Input Control Current                           | 50          | mA               |
| Peak (10ms)                                     | 1           | A                |
| Input Power Dissipation <sup>1</sup>            | 150         | mW               |
| Total Power Dissipation <sup>2</sup>            | 800         | mW               |
| ESD, Human Body Model                           | 8           | kV               |
| Isolation Voltage, Input to Output (60 Seconds) | 5000        | V <sub>rms</sub> |
| Operational Temperature, Ambient                | -40 to +85  | °C               |
| Storage Temperature                             | -40 to +125 | °C               |

<sup>1</sup> Derate linearly 1.33 mW / °C

<sup>2</sup> Derate output power linearly 6.67 mW / °C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Typical values are characteristic of the device at +25°C, and are the result of engineering evaluations. They are provided for information purposes only, and are not part of the manufacturing testing requirements.

## Electrical Characteristics @ 25°C

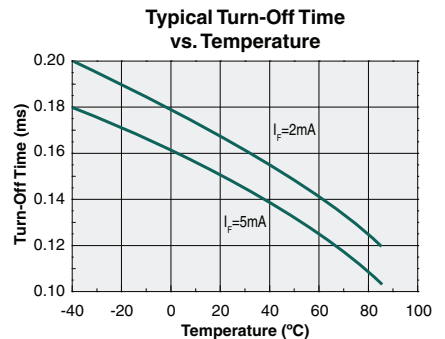
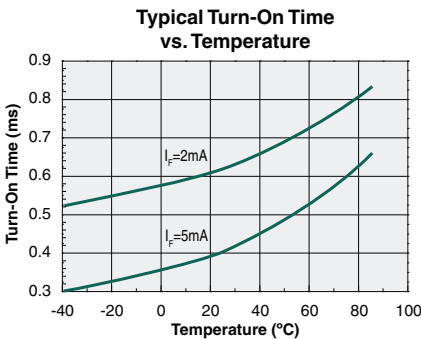
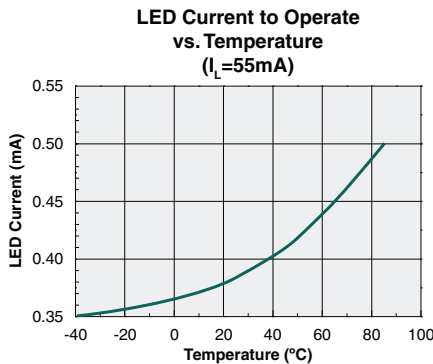
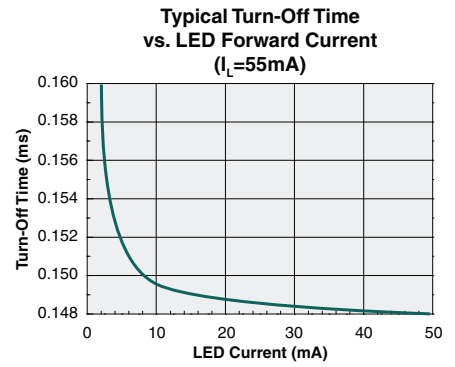
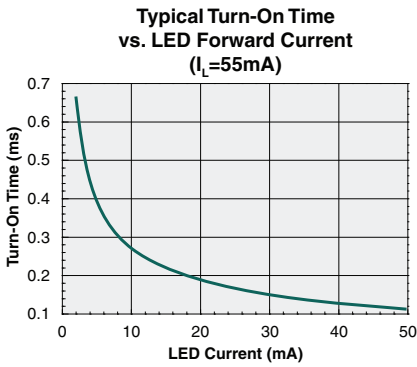
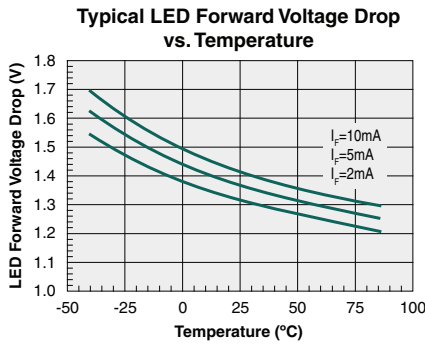
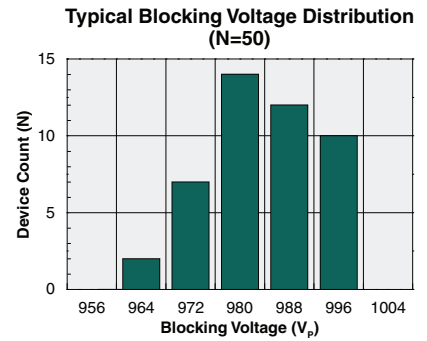
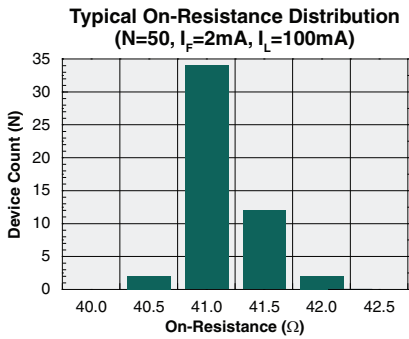
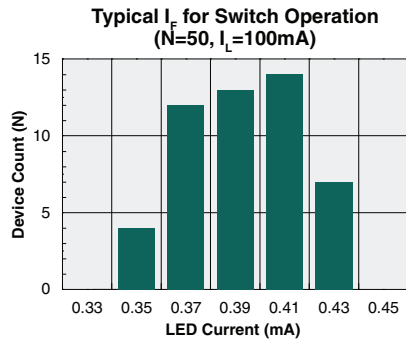
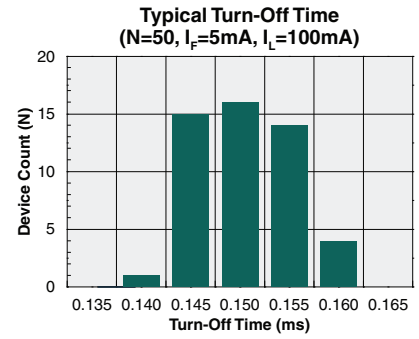
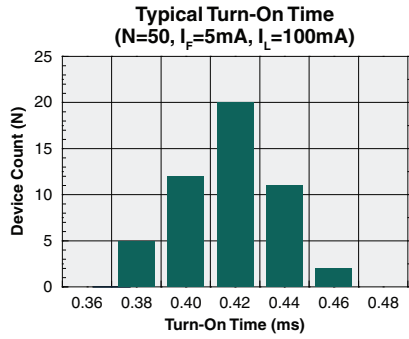
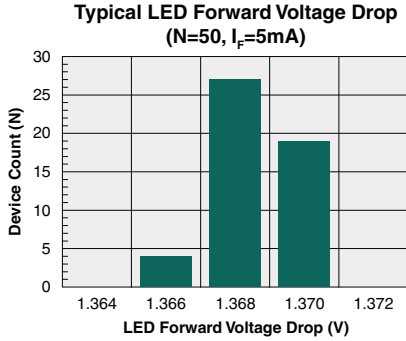
| Parameter                                      | Conditions                                       | Symbol            | Min | Typ  | Max  | Units                                |
|--|--|-------------------|-----|------|------|--------------------------------------|
| <b>Output Characteristics</b>                  |  |                   |     |      |      |                                      |
| Blocking Voltage                               | I <sub>L</sub> =1μA                              | V <sub>DRM</sub>  | 800 | -    | -    | V <sub>P</sub>                       |
| Load Current <sup>1</sup>                      |  |                   |     |      |      |                                      |
| Continuous                                     | I <sub>F</sub> =2mA                              | I <sub>L</sub>    | -   | -    | 100  | mA <sub>rms</sub> / mA <sub>DC</sub> |
| Peak   | I <sub>F</sub> =2mA, t=10ms                      | I <sub>LPK</sub>  | -   | -    | ±350 | mA <sub>P</sub>                      |
| On-Resistance <sup>2</sup>                     | I <sub>F</sub> =2mA, I <sub>L</sub> =100mA       | R <sub>ON</sub>   | -   | 40   | 50   | Ω                                    |
|  | I <sub>F</sub> =5mA, I <sub>L</sub> =1mA         |                   | -   | 70   | 85   |                                      |
| Off-State Leakage Current                      | I <sub>F</sub> =0mA, V <sub>L</sub> =800V        | I <sub>LEAK</sub> | -   | -    | 1    | μA                                   |
| Switching Speeds                               |  |                   |     |      |      |                                      |
| Turn-On  | I <sub>F</sub> =5mA, V <sub>L</sub> =10V         | t <sub>on</sub>   | -   | 0.42 | 5    | ms                                   |
| Turn-Off                                       |  | t <sub>off</sub>  | -   | 0.15 | 5    |                                      |
| Output Capacitance                             | I <sub>F</sub> =0mA, V <sub>L</sub> =50V, f=1MHz | C <sub>OUT</sub>  | -   | 11   | -    | pF                                   |
| <b>Input Characteristics</b>                   |  |                   |     |      |      |                                      |
| Input Control Current to Activate <sup>3</sup> | I <sub>L</sub> =100mA                            | I <sub>F</sub>    | -   | 0.39 | 2    | mA                                   |
| Input Control Current to Deactivate            | -  | I <sub>F</sub>    | 0.1 | -    | -    | mA                                   |
| Input Voltage Drop                             | I <sub>F</sub> =5mA                              | V <sub>F</sub>    | 0.9 | 1.36 | 1.5  | V                                    |
| Reverse Input Current                          | V <sub>R</sub> =5V                               | I <sub>R</sub>    | -   | -    | 10   | μA                                   |
| <b>Common Characteristics</b>                  |  |                   |     |      |      |                                      |
| Input to Output Capacitance                    | V <sub>IO</sub> =0V, f=1MHz                      | C <sub>IO</sub>   | -   | 3    | -    | pF                                   |

<sup>1</sup> Load derates linearly from 100mA @ 25°C to 55mA @ 85°C.

<sup>2</sup> Measurement taken within one second of on-time.

<sup>3</sup> For applications requiring high temperature operation (greater than 60°C) a minimum LED drive current of 5mA is recommended.

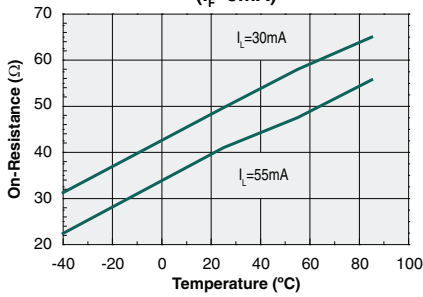
**PERFORMANCE DATA\***



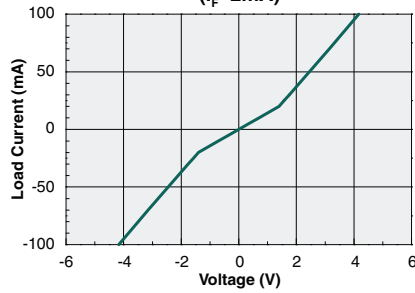
\*Unless otherwise noted, data presented in these graphs is typical of device operation at 25°C.

**PERFORMANCE DATA\***

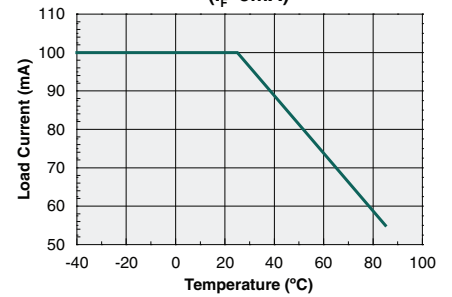
**Typical On-Resistance vs. Temperature**  
( $I_F=5mA$ )



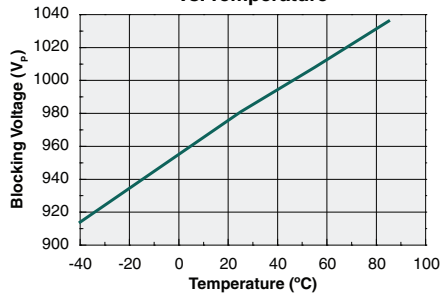
**Typical Load Current vs. Load Voltage**  
( $I_F=2mA$ )



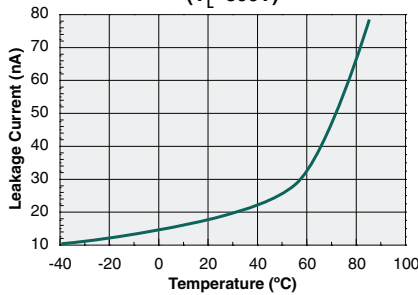
**Maximum Load Current vs. Temperature**  
( $I_F=5mA$ )



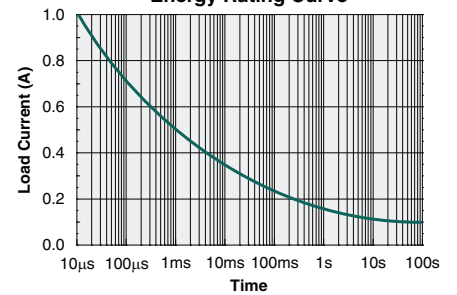
**Typical Blocking Voltage vs. Temperature**



**Typical Leakage Current vs. Temperature**  
( $V_L=800V$ )



**Energy Rating Curve**



\*Unless otherwise noted, data presented in these graphs is typical of device operation at 25°C.

## Manufacturing Information

### Moisture Sensitivity



All plastic encapsulated semiconductor packages are susceptible to moisture ingress. IXYS Integrated Circuits classifies its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL)** classification as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

| Device  | Moisture Sensitivity Level (MSL) Classification |
|---------|---|
| PLA171P | MSL 1   |

### ESD Sensitivity



This product is ESD Sensitive, and should be handled according to the industry standard **JESD-625**.

### Soldering Profile

Provided in the table below is the **IPC/JEDEC J-STD-020** Classification Temperature ( $T_C$ ) and the maximum total dwell time ( $t_p$ ) in all reflow processes that the body temperature of these surface mount devices may be ( $T_C - 5$ )°C or greater. The device's body temperature must not exceed the Classification Temperature at any time during reflow soldering processes.

| Device  | Classification Temperature ( $T_C$ ) | Dwell Time ( $t_p$ ) | Max Reflow Cycles |
|---------|--------------------------------------|----------------------|-------------------|
| PLA171P | 260°C                                | 30 seconds           | 3                 |

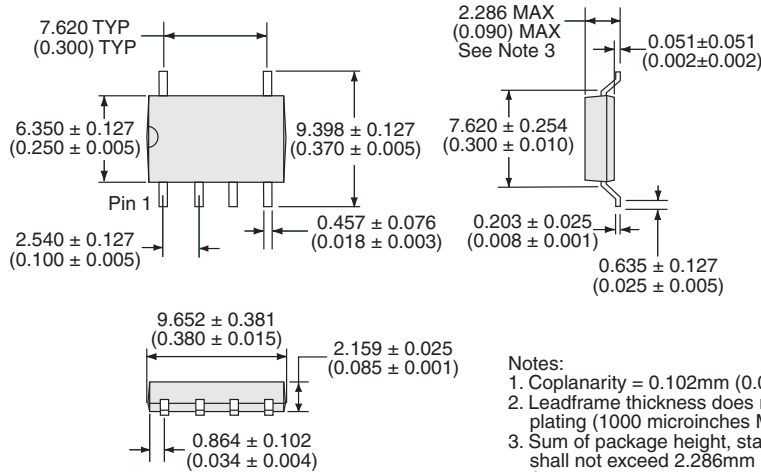
### Board Wash

IXYS Integrated Circuits recommends the use of no-clean flux formulations. Board washing to reduce or remove flux residue following the solder reflow process is acceptable provided proper precautions are taken to prevent damage to the device. These precautions include but are not limited to: using a low pressure wash and providing a follow up bake cycle sufficient to remove any moisture trapped within the device due to the washing process. Due to the variability of the wash parameters used to clean the board, determination of the bake temperature and duration necessary to remove the moisture trapped within the package is the responsibility of the user (assembler). Cleaning or drying methods that employ ultrasonic energy may damage the device and should not be used. Additionally, the device must not be exposed to halide flux or solvents.

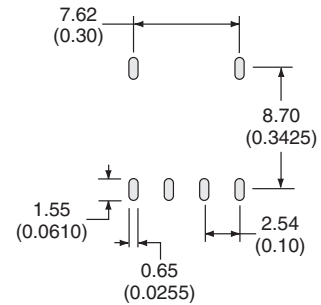


### Mechanical Dimensions

#### PLA171P



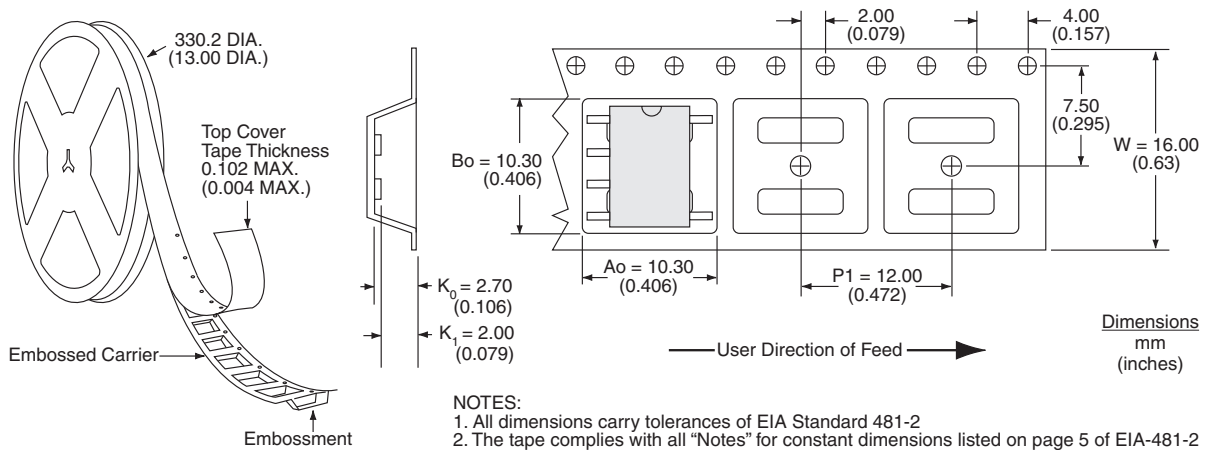
#### Recommended PCB Land Pattern



- Notes:
- Coplanarity = 0.102mm (0.004") MAX
  - Leadframe thickness does not include solder plating (1000 microinches MAX)
  - Sum of package height, standoff, and coplanarity shall not exceed 2.286mm (0.090")
  - Controlling dimension: Inches

Dimensions  
mm  
(inches)

#### PLA171PTR Tape & Reel



- NOTES:
- All dimensions carry tolerances of EIA Standard 481-2
  - The tape complies with all "Notes" for constant dimensions listed on page 5 of EIA-481-2
  - Controlling dimension: mm

For additional information please visit our website at: <https://www.ixysic.com>